DATA BOOK
PACKAGE OUTLINE

SUBSTRATE DRAWING
6576631

DRAFTER:	T. LEQUANG	DATE:	10/09/2013
DESIGNER:		DATE:	
CHECKER:	K. SINCERBOX	DATE:	10/09/2013
ENGINEER:	D. LEWIS	DATE:	10/09/2013
APPROVED:	E. REY	DATE:	10/09/2013
RELEASED:	WDM	DATE:	10/2013
TEMPLATE INFO:	EDGE# 4218519 REV A	DATE:	03/20/2013

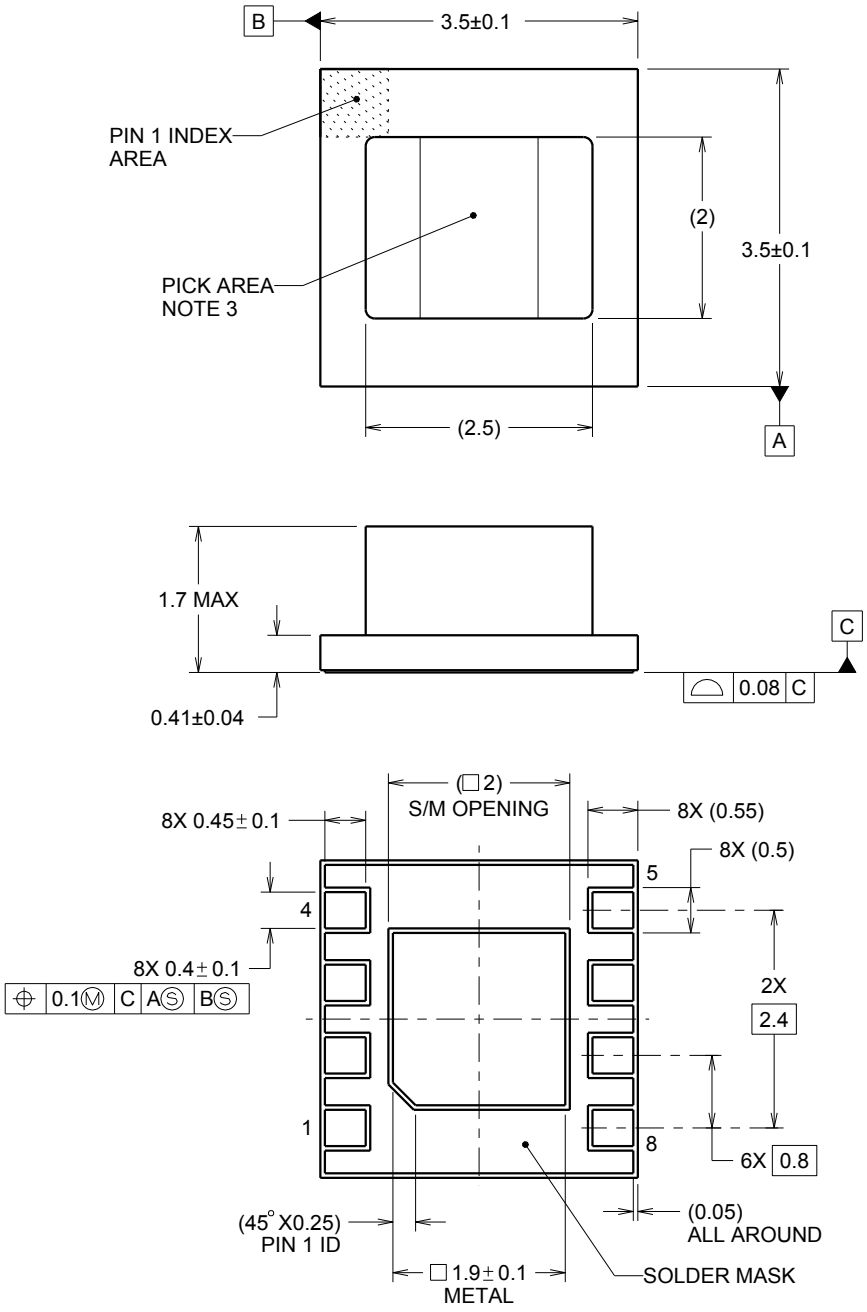
DIMENSIONS IN MILLIMETERS

TEXAS INSTRUMENTS
SEMICONDUCTOR OPERATIONS

CODE IDENTITY NUMBER
01295

ePOD, SIL0008B / MicroSiP™, 8 PIN, 0.8 MM PITCH

SCALE	SIZE		REV	PAGE
	A	4221020	A	1 OF 5



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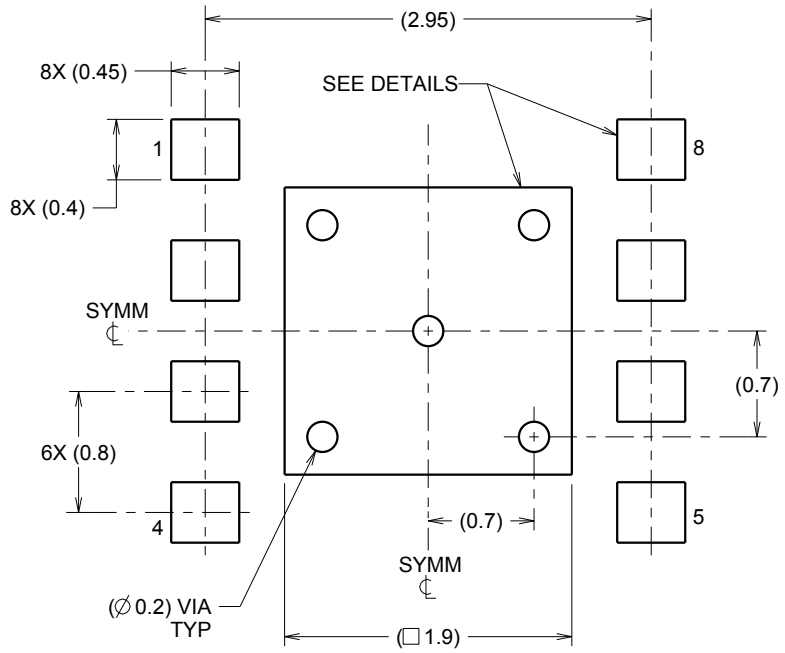
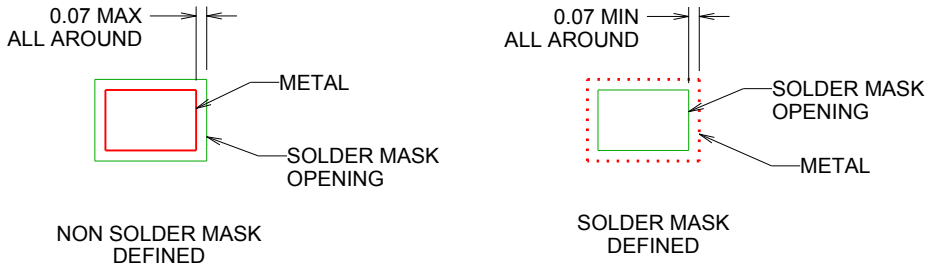
NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Pick and place nozzle ∅ 1.3 mm or smaller recommended.



LAND PATTERN EXAMPLE
1:1 RATIO WITH PACKAGE SOLDER PADS
SCALE:20X



SOLDER MASK DETAILS
NOT TO SCALE

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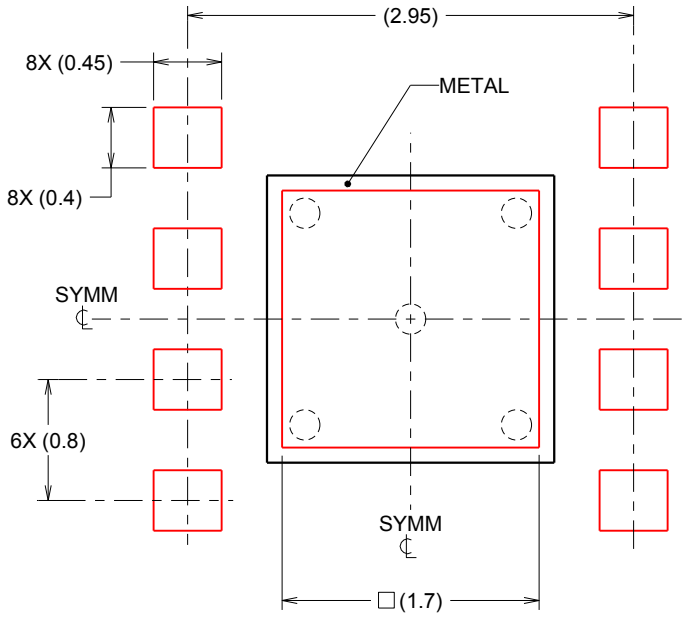
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, refer to QFN/SON PCB application note in literature No. SLUA271 (www.ti.com/lit/slua271).



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
80% PRINTED SOLDER COVERAGE BY AREA
SCALE:20X

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NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2136833	10/09/2013	D. LEWIS / T. LEQUANG